Strain Gage Adhesives

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For technical questions, contact: micro-measurements@vishaypg.com
General Information and Selection Guide

Because a strain gage can perform no better than the adhesive with which it is bonded to the test member, the adhesive is a vitally important component in every strain gage installation. Although there is no single adhesive ideally suited to all applications, Micro-Measurements offers a wide selection of adhesives to cover the spectrum of stress analysis testing, and for use in transducer manufacturing. Micro-Measurements adhesives are specially formulated and selected for highest performance under the recommended environmental conditions, and are packaged to provide for ease of mixing and application.

Each adhesive is accompanied by specific instructions for its proper handling — storage, mixing, application, curing, and, if appropriate, post-curing. The adhesive containers are also dated to assure freshness of the contents.

**Types and Features**

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<th>Adhesive</th>
<th>Description</th>
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<td>Most widely used general-purpose adhesive. Easiest to handle. Fast room-temperature curing.</td>
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<tr>
<td>M-Bond AE-10</td>
<td>General-purpose adhesive that is highly resistant to moisture and most chemicals. Room-temperature curing.</td>
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<tr>
<td>M-Bond AE-15</td>
<td>Similar to AE-10. Recommended for more critical applications, including transducer gaging. Moderately elevated-temperature curing.</td>
</tr>
<tr>
<td>M-Bond 610</td>
<td>Used primarily in stress analysis applications over a wide temperature range, and in precision transducers. Elevated-temperature curing.</td>
</tr>
<tr>
<td>M-Bond 600</td>
<td>Similar to 610, but faster reacting. Can be cured at somewhat lower temperatures than 610.</td>
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<tr>
<td>M-Bond 43-B</td>
<td>Normally used in precision transducers. Highly resistant to moisture and chemical attack. Elevated-temperature curing.</td>
</tr>
<tr>
<td>M-Bond GA-2</td>
<td>Special-purpose adhesive primarily used on very rough and irregular surfaces. Room-temperature curing.</td>
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<tr>
<td>M-Bond GA-61</td>
<td>Special-purpose adhesive with a higher operating temperature range than GA-2, and more viscous. Also used to fill irregular surfaces and to anchor leadwires. Elevated-temperature curing.</td>
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<tr>
<td>M-Bond A-12</td>
<td>Special-purpose, very high-elongation adhesive. Used only when other adhesives cannot meet elongation requirements. Elevated-temperature curing.</td>
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<tr>
<td>M-Bond 300</td>
<td>Special-purpose polyester adhesive used primarily when low-temperature curing is required. Sensitive to solvents. Not recommended as a general-purpose adhesive.</td>
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<tr>
<td>M-Bond 450</td>
<td>Special-purpose, high-performance epoxy for higher-temperature transducer applications.</td>
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<tr>
<td>Denex #3 Adhesive</td>
<td>One-part epoxy for lab and transducer work requiring minimal creep. Elevated temperature curing.</td>
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<tr>
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<td>Used for long term, high temperature applications requiring a filled glueine. Wider temperature range than GA-61.</td>
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<td>Single-part solvent thinned polyimide adhesive. Excellent for long-term high temperature applications.</td>
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<tr>
<td>GC Cement</td>
<td>Single-part ceramic cement used for free-filament gages. Recommended for use on low TCE materials, such as carbon.</td>
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<tr>
<td>H Cement</td>
<td>One-part ceramic cement/coating used for free filament strain gages. Good adhesion to most metals.</td>
</tr>
<tr>
<td>PBX Cement</td>
<td>Two-part ceramic cement/coating used for free-filament strain gages. Good adhesion to most metals.</td>
</tr>
<tr>
<td>Sauereisen #8 Cement</td>
<td>Single-part chemical setting zircon-based cement used for free-filament strain gages. High electrical insulation and thermal conductivity.</td>
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**Note:** It is usually misguided economy to attempt installing strain gages with outdated adhesive, or adhesive that has not been stored as recommended. It should also be noted that conventional industrial and consumer adhesives are not generally suitable for bonding strain gages. Since different adhesives are intended for different types of applications and different environmental conditions, it is obviously important to select the most appropriate adhesive for each strain measurement task. The table below lists all of the Micro-Measurements adhesives, while the table on the following page is provided as a guide for selecting the most appropriate adhesive for compatibility with a particular strain gage series and test environment.
General Information and Selection Guide

The two most important considerations for proper adhesive selection are compatibility with the backing material of the strain gage, and the operating temperature range over which the bond is expected to perform.

The chart below defines the recommended adhesive(s) for use with a particular strain gage series over various operating temperature ranges. When more than one adhesive is listed for a particular gage/test condition, preference would be given to the adhesive that is easiest to apply while still meeting all of the other performance criteria.

In addition to the primary adhesive selection criteria presented here, other factors (such as test duration, cyclic endurance required, and accuracy required) may have to be considered in the test profile. Detailed selection criteria are addressed in Tech Note TN-505, "Strain Gage Selection — Criteria, Procedures, Recommendations". There are many times when the interaction of test characteristics is too complex for selecting the proper adhesive from a chart with a high degree of confidence. In these cases, contact our Applications Engineering Department for recommendations.

### RECOMMENDED ADHESIVES/STRAIN GAGE SERIES

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<td>200 or AE-10 or AE-15</td>
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<tr>
<td></td>
<td>-50° to +400°F [-45° to +205°C]</td>
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<tr>
<td></td>
<td>-452° to +450°F [-269° to +230°C]</td>
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<td>610</td>
</tr>
<tr>
<td></td>
<td>&lt;600°F [-315°C]</td>
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<td>610</td>
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<tr>
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<tr>
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<td>CEA, EA</td>
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<td></td>
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<td></td>
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</tr>
<tr>
<td></td>
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<td>610, 450, P Adhesive</td>
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<tr>
<td></td>
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<td>ZC</td>
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</table>
M-Bond 200

Micro-Measurements

Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND 200 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape

DESCRIPTION

For routine experimental stress analysis applications under temperate environmental conditions, M-Bond 200 adhesive is ordinarily the best choice. This adhesive is very easy to handle, and cures almost instantly to produce an essentially creep-free, fatigue-resistant bond, with elongation capability of five percent or more.

M-Bond 200 is a cyanoacrylate that has been pretested and certified for use in bonding strain gages. It is an excellent general-purpose adhesive for laboratory and short-term field applications. The procedure for making a strain gage installation with M-Bond 200 is illustrated and described in detail in Instruction Bulletin B-127 included in each kit of adhesive.

The user should note that the performance of the adhesive can be degraded by the effects of time, humidity conditions, elevated temperature, and moisture absorption. Because of the latter effect, strain gage installations should always be covered with a suitable protective coating. When necessitated by more rigorous test requirements and/or environmental conditions, consideration should be given to one of the M-Bond epoxy adhesives, using the “Recommended Adhesives/Strain Gage Series” chart.

CHARACTERISTICS

Cure Requirements:
One-minute thumb pressure, followed by a minimum two-minute delay before tape removal. Bond strength increases rapidly during first five minutes. Cure time must be extended under conditions of low temperature (<70°F [<21°C]) or low humidity (<40% RH).

Operating Temperature Range:
- Short Term: −300° to +200°F [−185° to +95°C].
- Long Term: −25° to +150°F [−32° to +65°C].

Elongation Capabilities:
>5% at +75°F [+24°C], 3% at +75°F [+24°C] when used with CEA or EA/Option E strain gages.

Shelf Life:
Minimum 3 months at +75°F [+24°C] after opening, with cap replaced immediately after each use. Shelf life refers to the duration of time, beginning on date of shipment, over which properly stored adhesive should be expected to meet published specifications.

Note: To ensure a proper seal, wipe bottle spout clean and dry before replacing cap.

May be stored unopened up to 3 months at +75°F [+24°C] or 6 months at +40°F [+5°C].

Note: Condensation rapidly degrades adhesive performance and shelf life; after refrigeration, allow adhesive to reach room-temperature before opening. Refrigeration after opening is not recommended.

PACKAGING OPTIONS

Kit:
1 bottle [1 oz/28g] Adhesive
1 brush-cap bottle [30ml] Catalyst
polyethylene dispenser cap

Bulk:
Adhesive — 1 bottle [1oz/28g]
Adhesive — 5 tubes [2g each]
Adhesive — 16 bottles [1oz/28g each]
Catalyst — 12 brush-cap bottles [30ml each]
Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND AE-10 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Two-component, 100%-solids epoxy system for general-purpose stress analysis. Transparent, medium viscosity. Cure time as low as six hours at +75°F [+24°C] may be used. Elevated-temperature postcure is recommended for maximum stability, and/or tests above room temperature. Highly resistant to moisture and most chemicals, particularly when postcured. For maximum elongation, bonding surface must be roughened. Cryogenic applications require very thin gluelines.

CHARACTERISTICS
Operating Temperature Range:
Long Term: −320°F to +200°F [−195°C to +95°C].

Elongation Capabilities:
1% at −320°F [−195°C];
6% to 10% at +75°F [+24°C];
15% at +200°F [+95°C].

Shelf Life:
Minimum 12 months at +75°F [+24°C]; or 18 months at +40°F [+5°C]. If crystals form in resin jar, heat to +120°F [+50°C] for 30 minutes. Cool before mixing.

Pot Life:
15 to 20 minutes at +75°F [+24°C]. Can be extended by cooling jar or by spreading adhesive on clean aluminum plate.

Clamping Pressure:
5 to 20psi [35 to 140kN/m²].

Cure Requirements:
Preferred Room-Temperature Cure: 24-48 hours at +75°F [+24°C].
Recommended Postcure: 2 hours at 25°F [15°C] above maximum operating temperature.

PACKAGING
Kit:
- 6 mixing jars [10g ea] Resin
- 1 bottle [15ml] Curing Agent 10
- 6 calibrated pipettes
- 6 stirring rods

Bulk:
- 200g Resin
- 40g Curing Agent 10
- 3 calibrated pipettes

Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND AE-15 INSTALLATION:

- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION

Two-component, 100%-solids epoxy system for general-purpose stress analysis. Transparent, medium viscosity. Cure time as low as six hours at +125°F [+50°C]. Recommended for more critical applications, including transducers. It has a longer pot life than M-Bond AE-10 which allows more time for multiple gage installations. Elevated-temperature postcure is recommended for maximum stability, and/or tests above room temperature. Highly resistant to moisture and most chemicals, particularly when postcured. For maximum elongation, bonding surface must be roughened. Cryogenic applications require very thin gueelines.

CHARACTERISTICS

Operating Temperature Range:
Long Term: -452°F [-269°C]; to +175°F [+80°C].
Transducers: to +175°F [+80°C].

Elongation Capabilities:
2% at -320°F [-195°C];
10% to 15% at +75°F [+24°C];
15% at +200°F [+95°C].

Shelf Life:
Minimum 12 months at +75°F [+24°C]; or 18 months at +40°F [+5°C]. If crystals form in resin jar, heat to +120°F [+50°C] for 30 minutes. Cool before mixing.

Pot Life:
1-1/2 hours at +75°F [+24°C].

Clamping Pressure:
5 to 20psi [35 to 140kN/m²].

Cure Requirements:
Recommended PostCure: 2 hours at 25°F [15°C] above maximum operating temperature.
Optimum Performance Transducer Postcure: 1 hour at +200°F [+95°C].

PACKAGING OPTIONS

Kit:
- 6 mixing jars [10g ea] Resin
- 1 bottle [15ml] Curing Agent 15
- 6 calibrated pipettes
- 6 stirring rods

Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND 610 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Two-component, solvent-thinned, epoxy-phenolic adhesive for high-performance applications, including high-precision transducers. Solids content 22%. Widest temperature range general-purpose adhesive available. Low viscosity, capable of gluelines <0.0002 in [0.005mm]. Extremely thin, hard, void-free gluelines minimize creep, hysteresis, and linearity problems. Cure must begin within four hours of application.

CHARACTERISTICS

Operating Temperature Range:
- Short Term: -452°F to +700°F [-269° to +370°C].
- Long Term: -452°F to +500°F [-269° to +260°C].

Transducers: to +450°F [+230°C].

Elongation Capabilities:
- 1% at -452°F [-269°C];
- 3% at +75°F [+24°C];
- 3% at +500°F [+260°C].

Shelf Life:
Minimum 9 months at +75°F [+24°C]; or 15 months at +40°F [+5°C].

Pot Life:
6 weeks at +75°F [+24°C]; 12 weeks at +40°F [+5°C].

Clamping Pressure:
10 to 70psi [70 to 480kN/m²].
30 to 40psi optimum [200 to 275kN/m²].

Cure Requirements:
- Recommended Postcure: 2 hours at 50° to 75°F [30° to 40°C] above maximum operating temperature or cure temperature, whichever is higher.
- High Precision Transducer Postcure: 2 hours at +400° to +450°F [+205° to +230°C] after wiring.

PACKAGING OPTIONS

Kit:
- 4 bottles [11g ea] Curing Agent
- 4 bottles [14g ea] Resin
- 4 brush caps for dispensing mixed adhesive
- 4 disposable mixing funnels

Single Mix Kit:
- 1 bottle [11g ea] Curing Agent
- 1 bottle [14g ea] Resin
- 1 brush cap for dispensing mixed adhesive
- 1 disposable mixing funnel


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**Strain Gage Adhesive**

**OTHER ACCESSORIES USED IN AN M-BOND 600 INSTALLATION:**
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

**DESCRIPTION**

Similar to M-Bond 610 except with more reactive curing agent. Shorter shelf life, pot life, and working time than M-Bond 610, but has lower temperature cures and faster reaction time. Cure must begin within 30 minutes of application (up to 4 hours for M-Bond 610).

**CHARACTERISTICS**

**Operating Temperature Range:**
- **Short Term:** -452°F to +700°F [-269°C to +370°C].
- **Long Term:** -452°F to +500°F [-269°C to +260°C].

**Elongation Capabilities:**
- 1% at -452°F [-269°C];
- 3% at +75°F [+24°C];
- 3% at +500°F [+260°C].

**Shelf Life:**
Minimum 3 months at +75°F [+24°C]; or 9 months at +40°F [+5°C].

**Pot Life:**
2 weeks at +75°F [+24°C]; 4 weeks at +40°F [+5°C].

**Clamping Pressure:**
10 to 70psi [70 to 480kN/m²].
30 to 40psi optimum [200 to 275kN/m²].

**PACKAGING**

**Kit:**
- 4 bottles [11g ea] Curing Agent
- 4 bottles [8g ea] Resin
- 4 brush caps for dispensing mixed adhesive
- 4 disposable mixing funnels

**Single Mix Kit:**
- 1 bottle [11g ea] Curing Agent
- 1 bottle [8g ea] Resin
- 1 brush cap for dispensing mixed adhesive
- 1 disposable mixing funnel

**References:** Instruction Bulletin B-130, “Strain Gage Installations with M-Bond 43-B, 600 and 610 Adhesive Systems” included in each kit.

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND 43-B INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MIG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Single-component, solvent-thinned, epoxy adhesive normally used in transducer applications; solids content 25%. May be used both as an adhesive and as a protective coating. Capable of forming very thin, hard, void-free glue lines similar to M-Bond 610. Highly resistant to moisture and chemical attack.

CHARACTERISTICS
Operating Temperature Range:
- Short Term: −452°F to +350°F [−269°C to +175°C].
- Long Term: −452°F to +300°F [−269°C to +150°C].
- Transducers: to +250°F [+120°C].

Elongation Capabilities:
- 1% at −452°F [−269°C];
- 4% at +75°F [+24°C];
- 2% at +300°F [+150°C].

Shelf Life:
- Minimum 9 months at +75°F [+24°C]; or 18 months at +40°F [+5°C].

Pot Life:
- Minimum 9 months at +75°F [+24°C]; or 18 months at +40°F [+5°C].

Clamping Pressure:
- 15 to 100 psi [100 to 700 kN/m²].
- 40 to 50 psi [275 to 350 kN/m²] optimum.

Cure Requirements:
- Recommended: 2 hours at +375°F [+190°C], or as an alternate cure for aluminum alloy transducers, 2 1/2 hours at +300°F [+150°C].
- Recommended Transducer Postcure: 2 hours at +400°F [+205°C], or as an alternate postcure for aluminum alloy transducers 2 1/2 hours at +350°F [+175°C].

PACKAGING
Kit:
- 4 brush-cap bottles [30ml ea] premixed adhesive

Single Bottle:
- 1 brush cap bottle [30ml] premixed adhesive

References:

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND GA-61 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Two-component, partially filled, 100%-solids epoxy adhesive for general-purpose stress analysis. Very high viscosity. Widely used to fill irregular surfaces and to anchor leadwires. Forms a very hard, chemical-resistant material when fully cured. Glueline thickness is generally <0.002 in [0.05mm].

CHARACTERISTICS
- Operating Temperature Range:
  Short Term: –100°F to +600°F [–75°C to +315°C].
  Long Term: –100°F to +500°F [–75°C to +260°C].
- Elongation Capabilities:
  1% at –100°F [–75°C];
  2% at +75°F [+24°C];
  1% at +500°F [+260°C].
- Shelf Life:
  6 months minimum at +75°F [+24°C]; refrigeration recommended.
- Pot Life:
  10 hours at +75°F [+24°C]; increased by refrigeration, indefinite by freezing.
- Clamping Pressure:
  10 to 30psi [70 to 200kN/m²].

Cure Requirements:
- Elevated-Temperature Cure Required.
- Recommended Postcure: 1 hour at 50°F [30°C] above maximum operating temperature not to exceed +600°F [+315°C].

PACKAGING
- Kit:
  3 jars [10g ea] Resin
  3 jars [5g ea] Hardener
  3 stirring rods

References: Instruction Bulletin B-128, “Strain Gage Applications with M-Bond GA-61 Adhesive”, included in each kit.

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND GA-2 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Two-component, partially filled, 100%-solids epoxy system for general-purpose stress analysis. Higher viscosity than AE systems. Elevated-temperature cure recommended for best performance and resistance to chemical attack. Often used to fill irregular surfaces. Uneven gluelines easily detectable by nonuniformity of bond color.

CHARACTERISTICS
Operating Temperature Range:
Long Term: -320°F to +200°F [-195°C to +95°C].
Elongation Capabilities:
4% at -320°F [-195°C].
10% to 15% at +75°F [+24°C] after 40-hour RT cure or 6-hour RT cure with postcure.
Shelf Life:
Minimum 12 months at +75°F [+24°C]; or 18 months at +40°F [+5°C].
Pot Life:
15 minutes at +75°F [+24°C]. Can be extended by cooling jar or by spreading adhesive on clean aluminum plate.
Clamping Pressure:
5 to 20psi [35 to 140kN/m²]. The black filler provides a visual indication of nonuniform bond areas caused by uneven clamping pressure.

PACKAGING
Kit:
6 mixing jars [15g ea] Resin
6 calibrated pipettes
1 bottle [15ml] Curing Agent 10-A
6 stirring rods

M-Bond A-12
Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND A-12 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Two-component, 100%-solids epoxy system. Not intended as a general-purpose strain gage adhesive. Should be used only when maximum elongation requirements of a test exceed the capabilities of other M-Bond adhesive systems. Mixed adhesive gritty with large solid particles present; large particles must be removed prior to gage installation.

CHARACTERISTICS
Operating Temperature Range:
Long Term: –50° to +180°F [-45° to +80°C].
Elongation Capabilities:
15% to 20% at +75°F [+24°C].
Shelf Life:
Minimum 1 year at +75°F [+24°C].

Pot Life:
Approximately 1 hour.
Clamping Pressure:
5 to 20psi [35 to 140kN/m²].
Cure Requirements:
2 hours at +165°F [+75°C] or 2 weeks at +75°F [+24°C].

PACKAGING
Kit:
1 tube each Part A and Part B
5 disposable mixing cups
5 wooden stirring sticks

References: Application instructions for M-Bond A-12 are included in each kit.
Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND 300 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- PCT-2M Gage Installation Tape
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Special-purpose, two-component polyester adhesive. Not recommended as a general-purpose strain gage adhesive, but useful when a low-temperature-curing adhesive is required. While possessing the high shear strength required of a strain gage adhesive, peel strength and solvent sensitivity are relatively poor. Should not be used for impact strain measurements, or with solvent-thinned protective coatings.

CHARACTERISTICS

Operating Temperature Range:
- Long Term: −40° to +300°F [−40° to +150°C].

Elongation Capabilities:
- 1% to 2% at 75°F [24°C].

Shelf Life:
- Minimum 4 months at 75°F [24°C].

Pot Life:
- 15 to 20 minutes at +40°F [+5°C]; 5 to 8 minutes at 75°F [+24°C].

Clamping Pressure:
- 5 to 20 psi [35 to 140 kN/m²].

Cure Requirements:
- 24 hours at +40°F [+5°C];
- 18 hours at +60°F [+15°C];
- 12 hours at +75°F [+24°C].

PACKAGING

Kit:
- 6 mixing jars [10g ea] Resin
- 6 calibrated pipettes
- 1 bottle [6g] Catalyst
- 6 stirring rods

References: Instruction Bulletin B-133, "Strain Gage Installations with M-Bond 300 Adhesive", included in each kit.
Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN M-BOND 450 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
High-performance, two-component, solvent-thinned epoxy system specially formulated for high accuracy, elevated-temperature transducer applications.

CHARACTERISTICS

Operating Temperature Range:
- Short Term: −452°F to +750°F [-269 to +400°C].
- Long Term: −452°F to +500°F [-269 to +260°C].

Elongation Capabilities:
>5% at +75°F [+24°C].

Shelf Life:
Minimum 6 months at +75°F [+24°C].

Pot Life:
6 weeks at +75°F [+24°C].

Clamping Pressure:
60 to 100psi [415 to 690kN/m²].

Cure Requirements:
- Step 1: Air dry at +75°F [+24°C] 10 to 30 minutes.
- B-Stage: +225°F [+105°C] for 30 minutes.
- Cure: +350°F [+175°C] for 1 hour.

Recommended Postcure: 1 hour at 50°F [10°C] above maximum operating temperature in 50°F [30°C] increments from +350°F [+175°C], dwelling 1 hour at each step.

PACKAGING

Kit:
- 4 bottles [12.5g ea] Curing Agent
- 4 bottles [12.5g ea] Resin
- 4 brush caps for applying adhesive
- 4 disposable mixing funnels

References: Instruction Bulletin B-152, "Instructions for the Application of Micro-Measurements M-Bond 450 Adhesive", included in each kit.

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN A DENEX #3 INSTALLATION:
- CSM-1 Degreaser or GC-6 Isopropyl Alcohol
- Silicon Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Single-component, solvent thinned epoxy adhesive used in laboratory and transducer applications where negligible creep can be tolerated. Can be solvent thinned (acetone) for easy application. Lower creep at elevated temperatures. Can be B-staged or dried prior to clamped curing.

CHARACTERISTICS
Operating Temperature Range:
-452°F to +400°F [−269°C to +204°C].
Elongation Capability:
1% at +75°F [+24°C].
Shelf Life:
Minimum 1 year at +75°F [+24°C].
Pot Life:
Minimum 1 year at +75°F [+24°C].
Clamping Pressure:
30-50psi [200 to 350kN/m²].

Cure Requirements:
Laboratory Use: 1 hour at +250°F [+120°C], followed by 1 hr at +350°F [+175°C].
Transducers: 4 hours at +325°F [+160°C].

Posture (Unclamped):
Laboratory Use: 1 hour at 75°F [40°C] above maximum operating temperature.
Transducers: 4 hours at +350°F [+175°C].

PACKAGING OPTIONS
Kit:
1 brush cap bottle [1oz/30ml] of premixed adhesive.
4 brush cap bottles [1oz/30ml each] premixed adhesive.
1 bottle [32oz/950ml] premixed adhesive.

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN EPOXYLITE 813 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- MJG-2 Mykar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Two-part, 100%-solids, epoxy adhesive. Similar to GA-61, but serviceable to +600°F [+315°C]. Excellent adhesion to metals, ceramics, and most composites.

CHARACTERISTICS
Operating Temperature Range:
-320° to +600°F [-195° to +315°C].

Elongation Capabilities:
1% at +75°F [+24°C].

Shelf Life:
Minimum 6 months at +75°F [+24°C].

Pot Life:
6-8 hours at +75°F [+24°C].

Clamping Pressure:
30 to 70psi [200 to 350kN/m²].

Cure Requirements:
4 hours at +350°F [+175°C].

Recommended Posture (Unclamped):
1 hour at 25°F (15°C) above maximum operating temperature.

PACKAGING OPTIONS
Kits:
6 bottles Part A [0.5oz/18gm] Resin.
6 bottles Part B [0.25oz/7gm] Powder.

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Strain Gage Cement

OTHER ACCESSORIES USED IN A GC CEMENT INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- GT-11 Camel’s Hair Brush
- SPT-1 Double Blade Spatula

DESCRIPTION
Single-part ceramic cement for bonding free-filament strain gages (wire and foil). Recommended for installations on low-TCE materials such as carbon.

CHARACTERISTICS

| Operating Temperature Range: | -320° to +2000°F [-195° to +1093°C]. |
| Elongation Capabilities: | 0.5% at +75°F [+24°C]. |
| Shelf Life: | Minimum 1 year at +75°F [+24°C]. |
| Pot Life: | 1 year at +75°F [+24°C]. |

Temperature Coefficient of Expansion: 1.5ppm/°F [2.7ppm/°C].

Cure Requirements:
- **Precoat**: Air-dry 30 minutes at +75°F [+24°C], then 30 minutes at +200°F [+95°C] followed by 30 minutes at +300°F [+150°C].
- **Final Coat**: Air-dry 30 minutes at +75°F [+24°C], then 30 minutes at +200°F [+95°C] followed by 30 minutes at +300°F [+150°C], and final 1 hour at +600°F [+315°C].

PACKAGING OPTIONS

Kits:
1 bottle [1oz/30ml] premixed.
Strain Gage Cement

OTHER ACCESSORIES USED IN AN H CEMENT INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- GT-11 Camel's Hair Brush
- SPT-1 Double Blade Spatula
- H Cement Thinner

DESCRIPTION
Single-part ceramic cement/coating. Excellent electrical-insulation properties, even at +1600°F [+870°C]. Good adhesion to most metals.

CHARACTERISTICS

Operating Temperature Range:
−452°F to +1600°F [−269°C to +870°C].

Elongation Capabilities:
0.5% at +75°F [+24°C].

Shelf Life:
Minimum 1 year at +75°F [+24°C].

Pot Life:
Minimum 1 year at +75°F [+24°C].

Temperature Coefficient of Expansion
7.0ppm/F [13ppm/°C].

Cure Requirements:

Precocat:
Air-dry 30 minutes at +75°F [+24°C], then 30 minutes at +200°F [95°C] followed by 30 minutes at 350°F [177°C].

Final Coat:
Air-dry 30 minutes at +75°F [+24°C], then 30 minutes at +200°F [95°C] followed by 30 minutes at 350°F [177°C], and final 1 hour at +600°F [+315°C].

PACKAGING OPTIONS

Kits:
1 bottle [1oz/30ml] Cement
H Cement Kit A: 2 bottles [1oz/30ml] Cement
1 bottle [0.5oz/15ml] Thinner
1 bottle [2oz/60ml] Conditioner A
1 bottle [2oz/60ml] Neutralizer 5A
1 package 100-count CSP-1 Cotton Swabs
1 package 200-count GSP-1 Gauze Sponges
12 sheets [2in x 4.5in/50mm x 115mm]
of 400-grit Silicon-Carbide Paper

H Cement Kit B: Same as H Cement Kit A except 6 bottles [1oz/30ml] Cement
Strain Gage Adhesive

OTHER ACCESSORIES USED IN A P ADHESIVE INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbine Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- CSP-1 Cotton Swabs
- GSP-1 Gauze Sponges
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
Single-part, solvent-thinned, polyimide adhesive. Results in a strong, thin, near-creep-free, adhesive layer.

CHARACTERISTICS
Operating Temperature Range:
−452°F to +700°F [−270° to +370°C].
Upper limit:
+800°F [+425°C] for 1 to 2 hours.
Elongation Capabilities:
±2% at +75°F [+24°C].
Shelf Life:
Minimum 4 months at +75°F [+24°C].
Pot Life:
Minimum 4 months at +75°F [+24°C].
Clamping Pressure:
20 to 40psi [140 to 280kN/m²].

Cure Requirements:
For two minutes, expose the adhesive on the strain gage and test article to an infrared lamp or other heat source until the materials are dry. Monitor the temperature of the surface and do not allow materials to exceed +250°F [+120°C]. After clamping, cure 2 hours at +250°F [+120°C], increase temperature to +300°F [+150°C] for 2 hours, increase temperature to +340°F [+170°C] for 2 hours and finish cure with 4 hours at +380°F [+195°C].

Recommended Posture (Unclamped):
1 hour at +300°F [+150°C], followed by 2 hours at +400°F [+205°C], and then 4 hours at +500°F [+260°C].

PACKAGING OPTIONS
Kits:
1 brush-cap bottle [1oz/30ml]

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PBX Cement

Micro-Measurements

Strain Gage Cement

OTHER ACCESSORIES USED IN A PBX CEMENT INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- GT-11 Camel’s Hair Brush
- SPT-1 Double Blade Spatula

DESCRIPTION
Two-part ceramic cement/coating with excellent electrical insulating properties up to +1200°F [+650°C]. Recommended as a high-temperature cement and coating for free-filament strain gages (wire and foil) and thermocouple applications. Provides good adhesion to most metals.

CHARACTERISTICS
- Operating Temperature Range: −452° to +1200°F [−269° to +650°C].
- Elongation Capabilities:
  0.5% at +75°F [+24°C].
- Shelf Life:
  Minimum 1 year at +75°F [+24°C].
- Pot Life:
  Minimum 1 year at +75°F [+24°C].
- Temperature Coefficient of Expansion:
  7.0ppm/°F [13ppm/°C].
- Cure Requirements:
  **Precoat:** Air-dry 30 minutes at +75°F [+24°C], then 30 minutes at +200°F [95°C] followed by 30 minutes at +300°F [150°C].
  **Final Coat:** Air-dry 30 minutes at +75°F [+24°C], then 30 minutes at +200°F [95°C] followed by 30 minutes at +300°F [+150°C], and final 1 hour at +600°F [+315°C].

PACKAGING OPTIONS
- Kits:
  1 jar powder [1lb/454gm]
  1 bottle solvent [9oz/279ml]
Sauereisen DKS-8
Micro-Measurements

Strain Gage Cement

OTHER ACCESSORIES USED IN A SAUEREISEN DKS-8 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- CSP-1 Cotton Swabs
- GSP-1 Gauze Sponges
- GT-11 Camel’s Hair Brush
- SPT-1 Double Blade Spatula

DESCRIPTION
Single-part chemical-setting, inorganic, Zircon-based cement supplied as a powder and mixed with water. High electrical-insulation and thermal-conductivity values. Used for installing high-temperature free-filament strain gages.

CHARACTERISTICS

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating Temperature Range:</td>
<td>-452° to +2500°F [-269° to +1370°C]</td>
</tr>
<tr>
<td>Elongation Capabilities:</td>
<td>0.5% at +75°F [+24°C]</td>
</tr>
<tr>
<td>Shelf Life:</td>
<td>Minimum 1 year at +75°F [+24°C]</td>
</tr>
<tr>
<td>Pot Life:</td>
<td>Minimum 1 year at +75°F [+24°C]</td>
</tr>
<tr>
<td>Temperature Coefficient of Expansion:</td>
<td>2.6ppm/°F [4.7ppm/°C]</td>
</tr>
<tr>
<td>Cure Requirements:</td>
<td>18 to 24 hours at +75°F [+24°C]. Application of heat will accelerate cure time.</td>
</tr>
<tr>
<td>Recommended Postcure (Unclamped):</td>
<td>1 hour at 50°F [30°C] above maximum operating temperature.</td>
</tr>
</tbody>
</table>

PACKAGING OPTIONS

Kits:
1 bottle [4oz/115gm] powder
Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN RTC EPOXY INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- CSP-1 Cotton Swabs
- GSP-1 Gauze Sponges
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
General-purpose, two-component, adhesive for lab and field applications with post-yield, high-elongation strain gages. Also excellent for cryogenic strain measurement applications.

CHARACTERISTICS
Operating Temperature Range: 
-452° to +200°F [-269°C to +95°C].
Elongation Capabilities: ±15% at +75°F [+24°C].
Shell Life: Minimum 1 year at +75°F [+24°C].
Pot Life: 30 minutes at +75°F [+24°C].

Clamping Pressure: 5 to 20psi [35 to 140kN/m²].
Cure Requirements: 6 hours at +75°F [+24°C] or 1 hour at +175°F [+80°C].

PACKAGING OPTIONS
Kits:
1 jar Part A [2oz/56gm]
1 jar Part B [1oz/28gm]
1 jar Part A [11oz/308gm]
1 jar Part B [5oz/140gm]

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN AN EPY-500 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION

EPY-500 is a two-part, heat-curing, filled epoxy system that is specially formulated for Micro-Measurements. This adhesive has reduced particle size, allowing a much thinner glueline. The adhesive is compatible with all phenolic, epoxy-phenolic and polyimide strain gages.

CHARACTERISTICS

Operating Temperature Range:
-425° to +500°F [-269° to +260°C].

Clamping Pressure:
10 to 15 psi [70 to 105 kN/m²].

Cure Requirements:
22 hours at +200°F [+93°C]; or 4 hours at +250°F [+121°C]; or 1 hour at +350°F [+176°C]; or 1/2 hour at +400°F [+204°C].

Recommended Post Cure:
1 hour at +450°F [+232°C].

Strain Limit – Single Cycle:
-5% at +75°F [+24°C]; 1% at ~320°F [-195°C].

PACKAGING OPTIONS

Small Kit:
5 [10g ea] packages

Large Kit:
2 [50g ea] packages

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Strain Gage Adhesive

OTHER ACCESSORIES USED IN A QA-500 INSTALLATION:
- CSM Degreaser or GC-6 Isopropyl Alcohol
- Silicon-Carbide Paper
- M-Prep Conditioner A
- M-Prep Neutralizer 5A
- GSP-1 Gauze Sponges
- CSP-1 Cotton Applicators
- MJG-2 Mylar® Tape
- TFE-1 Teflon® Film
- HSC Spring Clamp
- GT-14 Pressure Pads and Backup Plates

DESCRIPTION
QA-500 is a specially formulated two-component, clear liquid and powder adhesive for use with strain gages. QA-500 has excellent moisture and chemical resistance.

CHARACTERISTICS

| Operating Temperature Range: | -320° to +500°F [-195° to +260°C]. |
| Shelf Life: | Minimum 9 months |
| Pot Life: | 24 hours |
| Strain Limit – Single Cycle: | 2% |
| Clamping Pressure: | 20 to 30psi [140 to 210kN/m²]. |
| Cure Requirements: | 2 hours at +250°F [+121°C] minimum. |
| Postcure: | (clamps removed) 4 hours at +50°F [+28°C] above maximum operating or curing temperature, whichever is higher. |

PACKAGING

Kit:
3 jars [7g ea] resin
3 jars [3g ea] hardener
3 stirring rods

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